

L Number	Hits	Search Text	DB	Time stamp
14	671	(257/697).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:37
16	812	(257/696).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:37
20	1108	(257/693).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:37
26	3120	tape with lead with frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:38
28	883	tape with ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:38
32	37201	chip with wire better with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:39
33	37101	chip with wire better with solder with cost and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:40
34	0	chip with wire with better with solder with cost and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:40
35	0	chip with wire with better with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:40
36	740	chip with wire with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:40
46	980	lead with frame with use	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:42
48	593	(361/813).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:42
49	269	((361/813).CCLS.) and lead adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:42
15	145	((257/697).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:42

17	59	((257/696).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:42
18	5	("3911475" "4001655" "4717948" "4758875" "4803543").PN.	USPAT	2002/09/09 15:42
19	6	5130780.URPN.	USPAT	2002/09/09 15:42
21	160	((257/693).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
22	15	("4965653" "5218234" "5291062" "5334857" "5355283" "5433822" "5468999" "5497032" "5552635" "5581122" "5598036" "5604379" "5640047" "5717252" "5731630").PN.	USPAT	2002/09/09 15:43
23	3	("5350947" "5352926" "5367435").PN.	USPAT	2002/09/09 15:43
24	5	5731630.URPN.	USPAT	2002/09/09 15:43
25	5	5731630.URPN.	USPAT	2002/09/09 15:43
27	25	tape with lead with frame with ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
29	145	(tape with ceramic with substrate) and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
30	62	glass adj epoxy with ceramic and tape and lead and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
31	17	glass adj epoxy with ceramic with heat and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
37	8	chip with wire with solder with design and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
38	5	(wire with bond with solder with design and (257/\$).ccls.) not (chip with wire with solder with design and (257/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
39	8	(wire with bond with solder with design and (257/\$).ccls.) not ((257/693).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
40	8	wire with bond with solder with design and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
41	20	Solder with wire with bumping and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43
42	5	Solder with wire with integration and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/09 15:43

43	3	6339260.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/09 15:43
44	41	wire with cost with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/09 15:43
45	2	6064116.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/09 15:43
47	171	(lead with frame with use) and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/09 15:43
50	70	((361/813).CCLS.) and lead adj frame) not semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/09 15:43